

**FEATURES**

- 2920 size, Surface mountable,
- Application: All high-density boards
- Operation Current: 300mA ~ 3.0A
- Maximum Voltage: 6V ~ 60V
- Temperature Range: -40°C to 85°C
- RoHS Compliant

**AGENCY RECOGNITION**

- UL (E211981)
- C-UL (E211981)
- TUV (R50090556)

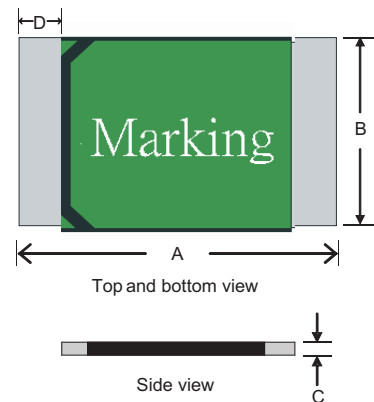
**ELECTRICAL CHARACTERISTICS (23°C)**

Part Number	Hold Current	Trip Current	Rated Voltage	Maximum Current	Typical Power	Max Time to Trip		Resistance Tolerance	
						Current	Time	R <sub>MIN</sub>	R <sub>1MAX</sub>
						I <sub>H</sub> , A	I <sub>T</sub> , A	V <sub>MAX</sub> , Vdc	I <sub>MAX</sub> , A
FSMD030-2920	0.30	0.60	60	10	1.5	1.5	3.0	1.000	4.80
FSMD050-2920	0.50	1.00	60	10	1.5	2.5	4.0	0.300	1.40
FSMD075-2920	0.75	1.50	33	40	1.5	8.0	0.3	0.180	1.00
FSMD100-2920	1.10	2.20	33	40	1.5	8.0	0.5	0.090	0.41
FSMD125-2920	1.25	2.50	33	40	1.5	8.0	2.0	0.050	0.25
FSMD150-2920	1.50	3.00	33	40	1.5	8.0	2.0	0.050	0.23
FSMD185-2920	1.85	3.70	33	40	1.5	8.0	2.5	0.040	0.15
FSMD200-2920	2.00	4.00	16	40	1.5	8.0	4.5	0.035	0.12
FSMD250-2920	2.50	5.00	16	40	1.5	8.0	16.0	0.025	0.085
FSMD260-2920	2.60	5.20	6	40	1.5	8.0	20.0	0.020	0.075

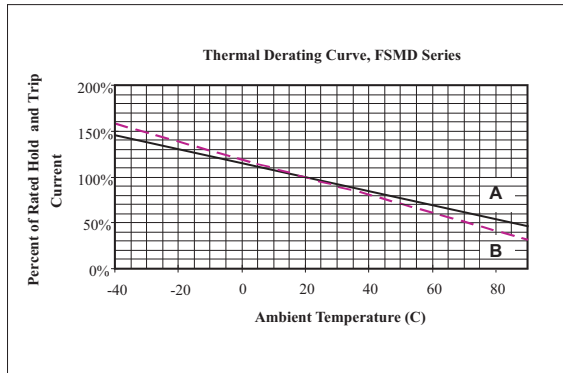
I<sub>H</sub>=Hold current-maximum current at which the device will not trip at 23°C still air.  
 I<sub>T</sub>=Trip current-maximum current at which the device will always trip at 23°C still air.  
 V<sub>MAX</sub>=Maximum voltage device can withstand without damage at its rated current (I<sub>MAX</sub>).  
 I<sub>MAX</sub>=Maximum fault current device can withstand without damage at rated voltage (V<sub>MAX</sub>).  
 P<sub>d</sub>=Typical power dissipated-type amount of power dissipated by the device when in the tripped state in 23°C still air environment.  
 R<sub>MIN</sub>=Minimum device resistance at 23°C prior to tripping.  
 R<sub>1MAX</sub>=Maximum device resistance at 23°C measured 1 hour post trip.  
 Termination pad characteristics  
 Termination pad materials: Tin-plated copper

**FSMD2920 PRODUCT DIMENSIONS (MILLIMETERS)**

Part Number	A		B		C		D
	Min	Max	Min	Max	Min	Max	Min
FSMD030-2920	6.73	7.98	4.80	5.44	0.60	1.15	0.35
FSMD050-2920	6.73	7.98	4.80	5.44	0.60	1.15	0.35
FSMD075-2920	6.73	7.98	4.80	5.44	0.35	1.15	0.35
FSMD100-2920	6.73	7.98	4.80	5.44	0.40	1.00	0.35
FSMD125-2920	6.73	7.98	4.80	5.44	0.40	0.90	0.35
FSMD150-2920	6.73	7.98	4.80	5.44	0.40	0.90	0.35
FSMD185-2920	6.73	7.98	4.80	5.44	0.30	0.90	0.35
FSMD200-2920	6.73	7.98	4.80	5.44	0.30	0.90	0.35
FSMD250-2920	6.73	7.98	4.80	5.44	0.30	0.90	0.35
FSMD260-2920	6.73	7.98	4.80	5.44	0.30	0.90	0.35

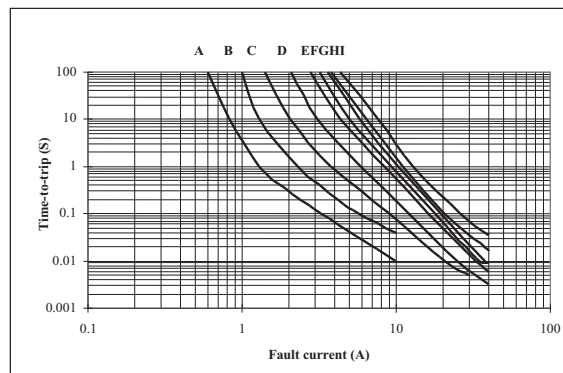


■ **THERMAL DERATING CURVE**



A= FSMD125 ~ FSMD260  
B= FSMD030 ~ FSMD100

■ **TYPICAL TIME-TO-TRIP AT 23°C**

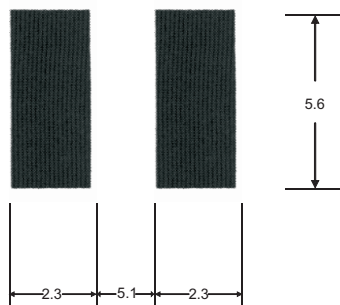


A = FSMD030-2920  
B = FSMD050-2920  
C = FSMD075-2920  
D = FSMD100-2920  
E = FSMD125-2920  
F = FSMD150-2920  
G = FSMD185-2920  
H = FSMD200-2920  
I = FSMD250-2920  
J = FSMD260-2920

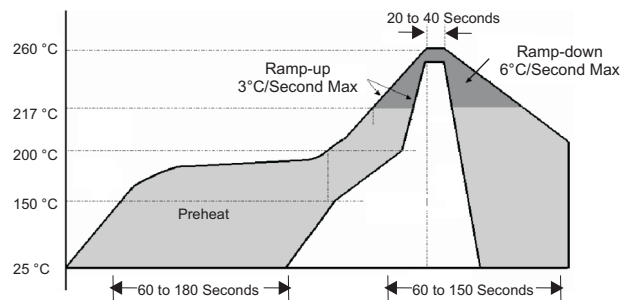
■ **PAD LAYOUTS, SOLDER REFLOW AND REWORK RECOMMENDATIONS**

The dimension in the table below provide the recommended pad layout for each FSMD2920 device

**NOMINAL PAD DIMENSIONS (MILLIMETERS)**



**Solder Reflow**



**Solder Reflow**

Due to "Lead Free" nature, up to 40 seconds dwelling time for the soldering zone is strongly recommended.

1. Recommended reflow methods; IR, vapor phase oven, hot air oven.
2. The FSMD Series are suitable for use with wave-solder application methods. (Top side only)
3. Recommended maximum paste thickness is 0.25mm.
4. Devices can be cleaned by using standard industry methods and solvents.
5. Storage Environment: <30°C / 60%RH

**Caution:**

If reflow temperatures exceed the recommended profile, devices may not meet performance requirements.

**Rework:**

Use standard industry practices.

**NOTE: All Specification subject to change without notice.**